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# Adhesive Properties **of Cured** Phenylethynyl *Containing* **Imides**

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# ADHESIVE PROPERTIES OF CURED PHENYLETHYNYL CONTAINING IMIDES

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## 1.ABSTRACT

As part of a program to develop structural adhesives for high performance aerospace applications, several phenylethynyl containing oligomer blends of LaRC™ MPEI<sup>1</sup> (Modified Phenylethynyl Terminated Polyimide) and a reactive plasticizer designated LaRC<sup>™</sup> LV-121 were prepared and evaluated. The fully imidized blends exhibited minimum melt viscosity as low as 1000 poise at 371°C. Ti/Ti lap shear specimens fabricated at 316°C under 15 psi gave RT strength of ~4300 psi and no change in strength was observed at 177°C. The chemistry and properties of this new MPEI as well as some blends of MPEI with LV-121 are presented and compared to the linear version, LaRC™-PETI-5.<sup>2,3</sup>

#### 2. EXPERIMENTAL

#### 2.1 Materials Synthesis

The MPEI was synthesized as previously reported.<sup>1</sup> The LV-121 was synthesized under the same conditions and utilizes similar chemistry as the MPEI but is a lower molecular weight phenylethynyl containing material.

### 2.2 Characterization

Brookfield viscosity measurements were taken on 35 and 42 wt% solids solutions at 25°C. Differential scanning calorimetry (DSC) was performed on a Shimadzu DSC-50 calorimeter at a heating rate of  $20^{\circ}$ C/min. The T<sub>a</sub> was taken at the inflection point of the heat flow vs. temperature curve.

## 2.3 Rheology

Melt viscosity measurements were performed on a Rheometrics System IV rheometer. Sample specimen disks, 1 inch in diameter and  $\sim$  0.06 inch thick, were prepared by press molding of solution imidized powder at RT. The compacted resin disk was then loaded in the rheometer fixture with 1 inch parallel plates. The top plate was oscillated at a fixed strain rate of 5% and a fixed angular frequency of 10 rad/sec, while the lower plate was attached to a transducer which recorded the resultant torque. Storage (G') and loss (G") moduli as a function of time (t) were measured at several temperatures.

#### 2.4 Films

**Poly(amide** acid) solutions were poured onto clean glass plates and spread to -30 mils thickness using a doctor's blade, then placed in a level, dust free, dry chamber until tack free. Films were cured in a circulating air oven for 1 hour each at 100, 225, and 350°C, removed from the glass plates and tested according to ASTM-D882.

#### 2.5 Adhesive Specimens

NMP solutions (35% solids) were used to coat 112 E-glass (A1100 finish). Each coat was dried in a circulating air oven at 100 and 225°C for 1 h each. Several coats were used to provide a 12-14 mil thick tape with final volatile content of <1.5%. Titanium (Ti,6AI-4V) coupons (Pasa-Jell 107™ surface treatment, primed with PETI-5 solution) were bonded under 1.7 - 50 psi by heating rapidly to 288 - 371 °C and holding for 1 - 8 h. Four specimens of each bonding condition were tested at RT and 177°C following the guidelines of ASTM D-1002.

#### 3. RESULTS AND DISCUSSION

Although several new MPEI compositions and different molecular weights (from 1500 to 7000 g/mole theoretical number average molecular weights) have been

prepared, the **work** presented herein describes **only** one composition and at **only one** molecular weight. This composition utilizes BPDA with 85% 3,4-ODA and 15% APB such that the total theoretical number average molecular weight is 5500 g/mole. This particular material has received most of the attention because it provides a direct comparison to the completely linear version, PETI-5, of the same theoretical number average molecular weight. Likewise, many different LaRC™ LV compositions and molecular weights have been prepared, the LV-121 composition was chosen for the blends because of the similarities in chemistry with the MPEI.

The reactive plasticizers with similar composition to LV-121 but various molecular weights and their dynamic minimum melt viscosities are shown in Table 1. All the plasticizers exhibit low initial Tg and minimum melt viscosity of < 50 poise (below capability of equipment) at a temperature of ~260 °C.

As shown in Table 2, the MPEI has a higher cured  $T_q$  than PETI-5 by about 20°C when cured at either 350 or 371 °C for 1 h. Furthermore, film properties are higher at both RT and 177°C for the MPEI. Tensile strength at RT has improved by almost 25% while strength at 177°C has improved by over 15%. Tensile moduli at both RT and 177°C have increased by ~25% to very high values of 570 and 411 Ksi, respectively, when compared to PETI-5. There is a significant reduction in film elongation from 32% at RT for PETI-5 to 8% elongation for the MPEI material at RT.

Table 2 also shows both the melt and solution viscosities for the two materials. As shown, the MPEI has a minimum dynamic melt viscosity of 600 poise occurring at 335°C, a lower temperature by -35°C than the minimum for PETI-5. Furthermore, the concentrated solution viscosity (35% solids) is ~2000 centipoise versus 30,000 to 40,000 centipoise for the linear PETI-5. This difference can be very important when making prepreg or adhesive tape.

Table 3 shows titanium to titanium tensile shear strengths for the MPEI when

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bonded under several conditions. **The** adhesive tape had been dried to <1.5% volatile content at a final temperature of 250°C. Very good strengths were obtained at RT and there was little to no drop off in strengths when tested at 177°C. The 177°C strengths are comparable to PETI-5.

Table 4 shows titanium to titanium tensile shear strengths for the blends when bonded under several conditions. The RT strengths are lower than the MPEI in most cases but the 177°C strengths are comparable under some bonding conditions. The blends have lower melt viscosity and actually have significant adhesive strength when bonded under only 1.7 psi at 316°C.

Neat resin properties of PETI-5/LV-121 blends are shown in Table 5. The dynamic minimum viscosity had reduced from 60,000 to 7,000 poise for PETI-5 containing 10 wt.% of LV-121 plasticizer. The blends exhibit comparable LSS as PETI-5 at 177°C when processed at milder temperature and pressure which are more desirable for secondary bonding applications.

## 4. CONCLUSIONS

Blends of the MPEI and LaRC<sup>™</sup> LV-121 have been prepared and evaluated for adhesive application. The polymer blends exhibit excellent adhesive strengths and processability at 316 °C under low pressure. Blends of PETI-5 and LaRC™ LV-121 also exhibit excellent Ti/Ti lap shear strength retention at 177 °C and lower melt viscosities than the pure PETI-5, providing easier processing conditions.

#### 5. REFERENCE

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 $\bar{\mathbf{v}}$ 

 $\bar{\psi}$ 



# **Table** 1. Resin Properties of Reactive Plasticisers

<sup>a</sup> not detectable.

 $\hat{\mathcal{A}}$ 

 $\sim 10$ 

 $\omega$ 



# Table 2. Properties of MPEI<sup>1</sup> Compared to PETI-5.







 $\label{eq:2.1} \frac{1}{\sqrt{2}}\left(\frac{1}{\sqrt{2}}\right)^{2} \left(\frac{1}{\sqrt{2}}\right)^{2} \left(\$ 





# Table 5. Neat Resin Properties of PETI-5/LV 121 Blends and Ti/Ti Lap Shear Strength(LSS) at RT and (177°C)

 $\label{eq:2.1} \frac{1}{\sqrt{2}}\sum_{i=1}^n\frac{1}{\sqrt{2\pi}}\sum_{i=1}^n\frac{1}{\sqrt{2\pi}}\sum_{i=1}^n\frac{1}{\sqrt{2\pi}}\sum_{i=1}^n\frac{1}{\sqrt{2\pi}}\sum_{i=1}^n\frac{1}{\sqrt{2\pi}}\sum_{i=1}^n\frac{1}{\sqrt{2\pi}}\sum_{i=1}^n\frac{1}{\sqrt{2\pi}}\sum_{i=1}^n\frac{1}{\sqrt{2\pi}}\sum_{i=1}^n\frac{1}{\sqrt{2\pi}}\sum_{i=1}^n\frac{$  $\label{eq:2.1} \frac{1}{\sqrt{2}}\sum_{i=1}^n\frac{1}{\sqrt{2}}\sum_{i=1}^n\frac{1}{\sqrt{2}}\sum_{i=1}^n\frac{1}{\sqrt{2}}\sum_{i=1}^n\frac{1}{\sqrt{2}}\sum_{i=1}^n\frac{1}{\sqrt{2}}\sum_{i=1}^n\frac{1}{\sqrt{2}}\sum_{i=1}^n\frac{1}{\sqrt{2}}\sum_{i=1}^n\frac{1}{\sqrt{2}}\sum_{i=1}^n\frac{1}{\sqrt{2}}\sum_{i=1}^n\frac{1}{\sqrt{2}}\sum_{i=1}^n\frac$ 

 $\label{eq:2.1} \frac{1}{\sqrt{2}}\left(\frac{1}{\sqrt{2}}\right)^{2} \left(\frac{1}{\sqrt{2}}\right)^{2} \left(\$ 

